

**REMARKS**

The non-elected claims have been cancelled without prejudice to presentation in a continuing application.

Acknowledgement of receipt of the Japanese priority document is respectfully requested.

The indication that claims 2 and 17-19 are allowable in independent form is acknowledged with appreciation.

Claim 1 has been amended to increase its clarity. It is respectfully submitted that the expression "other than boron" clearly means that when boron is excluded, the sum total of all other elements present is 100%. Withdrawal of the Section 112 rejection is respectfully requested.

Claims 1, 3-7, and 16 were rejected under 35 USC § 103 over Miki in view of Piper. This rejection is respectfully traversed.

The claimed invention broadly comprises an electronic component body having an external electrode thereon, the external electrode comprising two sintered electrode layers containing different metals, in which the first sintered electrode layer comprises a first borosilicate glass containing 85% to 95% by weight of silicon and 0.5% to 1.5% by weight of the alkali metal, and the second sintered electrode layer comprises a second

borosilicate glass containing 65% to 80% by weight of silicon and 3.5% to 8.0% by weight of alkali metal.

Miki describes a component having a 3 layer external electrode in which the first layer on the component surface contains Si and an alkali metal. The electrode layer disposed on the first electrode layer is an electroplated layer (column 4, lines 10-13), and therefore does not contain any glass. The Piper disclosure is similar.

The assertion that the arrangement in both of these reference is the reverse of that claimed is not correct. A pair of two borosilicate glass sintered electrode layers is not the reverse of a sintered electrode layer topped by an electroplated layer which contains neither Si nor alkali metal.

The assertion that the passage in Miki at column 4, lines 26-32 teaches alkali metal enhances “platablility of the conduction paste” is also not correct since this passage concerns the adhesion of a conductor to a ceramic substrate (not to another conductor), and in any event, the second layer in this reference is made by electroplating and not by use of a conductive paste. Further, even adding an alkali metal to the electroplated metal for some unknown reason would still not result in the second layer containing Si.

Since the references in combination fail to teach or suggest an external electrode comprising two sintered electrode layers containing different metals and each containing borosilicate glass containing an alkali metal, the claimed invention is clearly unobvious.

Application No. 10/568,441  
Amendment dated  
Reply to Office Action of August 6, 2008

Docket No.: M1071.1956

In view of the above amendment, applicant believes the pending application is in condition for allowance.

Dated: November 3, 2008

Respectfully submitted,

By /Edward A. Meilman/  
Edward A. Meilman  
Registration No.: 24,735  
DICKSTEIN SHAPIRO LLP  
1177 Avenue of the Americas  
New York, New York 10036-2714  
(212) 277-6500  
Attorney for Applicant